

## An environmentally friendly, high functioning simple process

### Development by design

Organic surface finishes provide a solderable environmentally friendly finish for fabricators in the electronics industry. Key to the potency of the process is the amount of reflow cycles the finish can endure. Additionally the thickness of the coating is a key quality indicator or process control tool as it is a measure of potential for solder joint quality implications.

OS-Tech® can guarantee multiple solder reflow cycles whilst ensuring that the pretreatment can optimize the copper surface and therefore facilitate an even OSP coating. The benefits described above can all be achieved with a single step process.

### Features and benefits

- A 3 step low temperature process
- Application of Atotech equipment possible
- Team up with Atotech and our unique customer understanding within the electronics industry

# Introducing simplicity with the benefit of market grown confidence: OS-Tech®



Figure 1: Precipitation free processing for mass production

## Vertical and horizontal process sequences

	vertical	horizontal
<b>Cleaner</b>	ProSelect CT 1 - 2 min. @ 45 °C	ProSelect H 45 - 80 s @ 45 °C
<b>Rinse</b>	2 min. @ RT	60s @ RT
<b>Coppertreat 500</b>	60 s @ 35 °C Etch depth 1.0 - 1.2 µm	60 s @ 35 °C Etch depth 1.0 - 1.2 µm
<b>Rinse</b>	2 min. @ RT	60 s @ RT
<b>Dry</b>	Air knife	Air knife
<b>OS-Tech®</b>	60 s @ 40 °C 0.2 - 0.45 µm (FIB)	60 s @ 40 °C 0.2 - 0.45 µm (FIB)
<b>Rinse</b>	2 min. @ RT	60 s @ RT
<b>Dry</b>	15 min. @ 60 °C	60 s @ 65 °C

Figure 2: Simple processing sequence both vertically and horizontally

## Wetting performance vs. ageing at 50°C, 90% r.h for 96 hours

Number of holes filled & fill % vs. reflow cycles

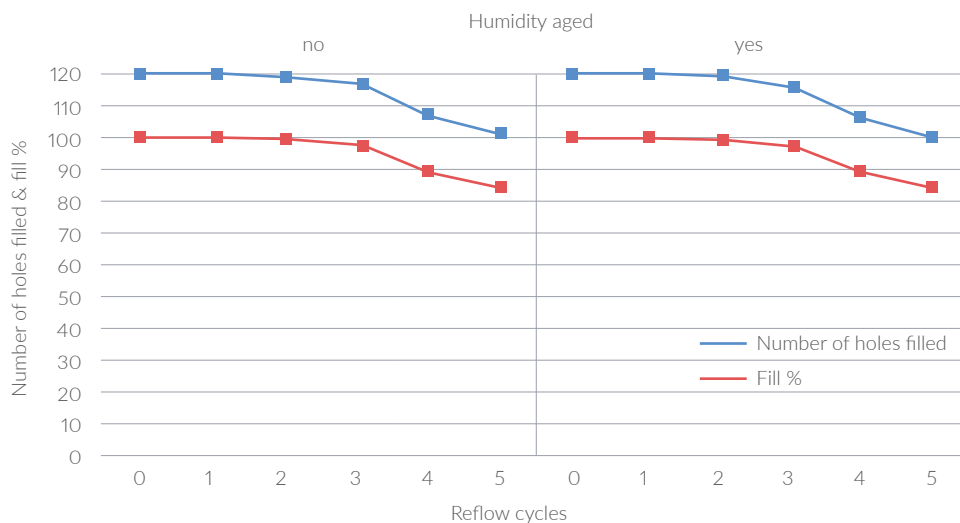


Figure 3: Unrivalled wave soldering capability even after ageing

